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3. The composition as claimed in claim 1 wherein said inorganic filler is a powdery silicious oxide.

4. The composition as claimed in claim 1 wherein said organohydrogenpolysiloxane is a methylhydrogenpolysiloxane.

5. The composition as claimed in claim 1 wherein said hydrazine compound is a monoalkylhydrazine.

6. The composition as claimed in claim 1 wherein said hydrazine compound is phenylhydrazine.

7. The composition as claimed in claim 1 wherein said hydrazine compound is β -methylphenylhydrazine.

8. The composition as claimed in claim 1 into which an organic peroxide is additionally incorporated in an amount of from 0.01 to 5 parts by weight based on 100 parts by weight of component (1).

9. A process for preparing the composition as claimed in claim 1 which comprises blending a mixture of components (1), (2) and (3) with the reaction product of components (4) and (5).

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10. A heat-curable organopolysiloxane composition comprising (1) 100 parts by weight of a methylvinylpolysiloxane containing at least two vinyl groups per molecule and having a viscosity exceeding 1,000 centistokes at 25° C, (2) from 10 to 200 parts by weight of a powdery silicious oxide, (3) a methylhydrogenpolysiloxane containing at least two Si-H linkages per molecule in an amount sufficient for giving the Si-H linkages from 0.5 to 15 times in number compared to the vinyl groups contained in component (1), (4) platinum or a platinum-containing compound in a catalytic amount, and (5) methylhydrazine or phenylhydrazine in an amount larger than 10 % by weight of the amount of compound (4) as platinum.

11. The composition as claimed in claim 10 into which an organic peroxide is additionally incorporated in an amount of from 0.01 to 5 parts by weight based on 100 parts by weight of component (1).

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